

P-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^a	Q _g (Typ.)			
- 60	0.055 at V _{GS} = - 10 V	- 7.0	30 nC			
- 00	0.065 at V _{GS} = - 4.5 V	- 6.0	30110			

FEATURES

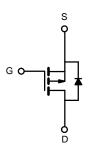
- TrenchFET® Power MOSFET
- 100 % UIS Tested

APPLICATIONS

Load Switch







P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS	- (1A - 20 0, unic			1111	
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V_{DS}	- 60	V	
Gate-Source Voltage		V_{GS}	± 20		
	T _C = 25 °C		- 7.0 ^a		
Continuous Drain Current (T _J = 150 °C)	T _C = 70 °C		- 5.2		
Continuous Diam Current (1) = 130 °C)	T _A = 25 °C	I _D	- 4.8 ^b	۸	
	T _A = 70 °C		- 4.1 ^b	A	
Pulsed Drain Current		I _{DM}	- 25		
Avalanche Current Pulse	L = 0.1 mH	I _{AS}	- 4.5		
Single Pulse Avalanche Energy	L = U.T IIII	E _{AS}	10.1	mJ	
Continuous Source-Drain Diode Current	T _C = 25 °C	1	6.9 ^a	^	
Continuous Source-Drain Diode Current	T _A = 25 °C	l _S	3.5 ^b	Α	
	T _C = 25 °C		10.4 ^a		
	T _C = 70 °C	D .	6.6 ^a	10/	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.1 ^b	W	
	T _A = 70 °C		1.1 ^b		
Operating Junction and Storage Temperature Ra	ange	T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	33	40	°C/W	
Maximum Junction-to-Case	Steady State	R _{thJC}	0.98	1.2	C/vv	

Notes:

- a. Based on T_C = 25 °C.
- b. Surface mounted on 1" x 1" FR4 board.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						•	
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 60			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	$\Delta V_{DS}/T_J$ $I_D = -250 \mu A$		68		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	i _D = - 250 μA		- 5.2		mv/·C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 1.0		- 2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	1	V _{DS} = -60 V, V _{GS} = 0 V			- 1		
	IDSS	V _{DS} = - 60 V, V _{GS} = 0 V, T _J = 55 °C			- 10	μA	
On-State Drain Current ^a	I _{D(on)}	V _{DS} = - 5 V, V _{GS} = - 10 V	- 25			Α	
Drain-Source On-State Resistance ^a	В	V _{GS} = - 10 V, I _D = - 3 A		0.055		Ω	
	R _{DS(on)}	V _{GS} = - 4.5 V, I _D = - 2 A		0.065			
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 15 V, I _D = - 5 A	20			S	
Dynamic ^b							
Input Capacitance	C _{iss}			1500			
Output Capacitance	C _{oss}	$V_{DS} = -25 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		200		pF	
Reverse Transfer Capacitance	C _{rss}			150			
Total Gata Chargo	Q_g	V _{DS} = - 30 V, V _{GS} = - 10 V, I _D = - 5 A		38	56	nC	
Total Gate Charge				19	30		
Gate-Source Charge	Q_{gs}	$V_{DS} = -30 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$		9			
Gate-Drain Charge	Q_{gd}			10			
Gate Resistance	R_{g}	f = 1 MHz		5.2		Ω	
Turn-On Delay Time	t _{d(on)}			10	15		
Rise Time	t _r	$V_{DD} = -2 V$, $R_L = 2 \Omega$		7	15	no	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 5 A, V_{GEN} = - 10 V, R_g = 1 Ω		70	110	ns	
Fall Time	t _f			40	60		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$	T _C = 25 °C		- 6.9	A	
Pulse Diode Forward Current ^a	I _{SM}				- 15		
Body Diode Voltage	V _{SD}	I _S = - 3 A		- 1	- 1.5	V	
Body Diode Reverse Recovery Time	t _{rr}			45	68	ns	
Body Diode Reverse Recovery Charge Q _{rr}		I _F = - 5 A, di/dt = 10 A/μs, T _{.I} = 25 °C		59	120	nC	
Reverse Recovery Fall Time	t _a	$ 1_F - 3_A, \text{ u/u} = 10_A/\mu s, 1_J = 23_C$		29		ns	
Reverse Recovery Rise Time	t _b			16			

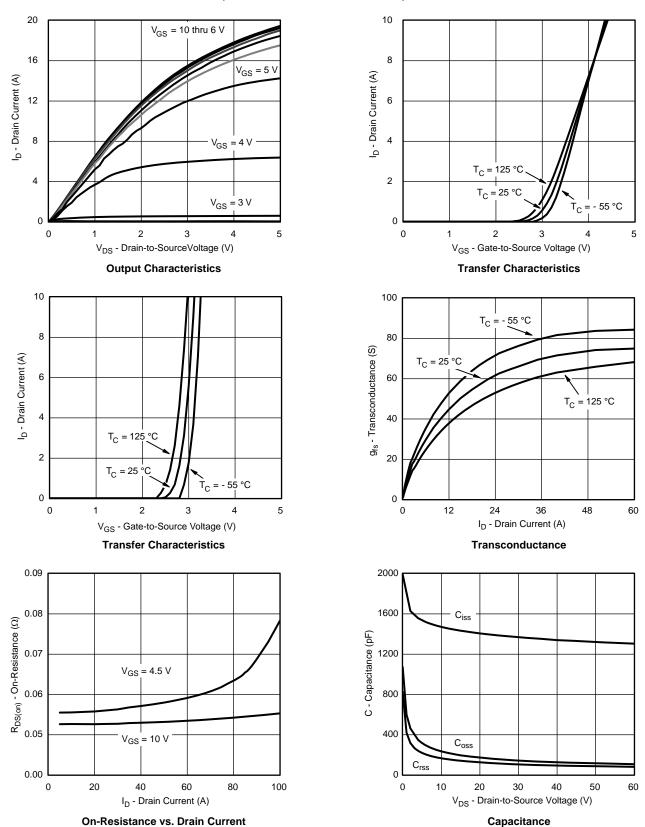
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

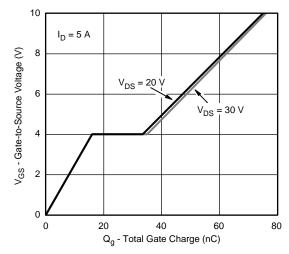


TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

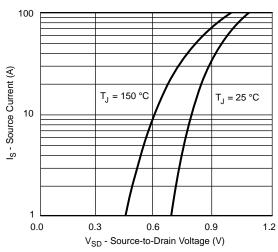




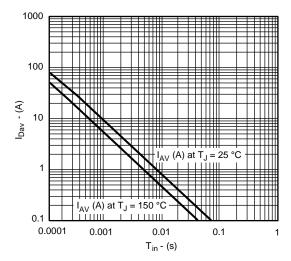
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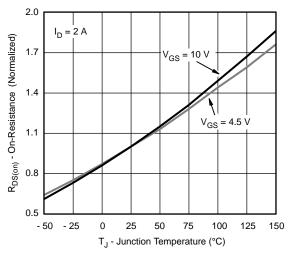
Gate Charge



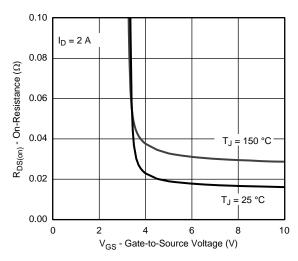
Source-Drain Diode Forward Voltage



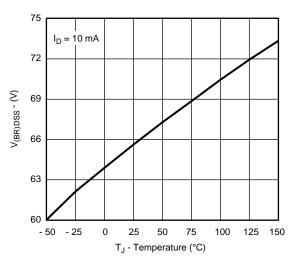
Single Pulse Avalanche Current Capability vs. Time



On-Resistance vs. Gate-to-Source Voltage



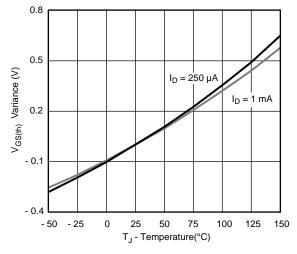
On-Resistance vs. Gate-to-Source Voltage

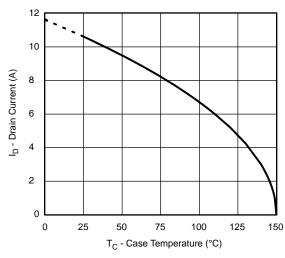


Drain-Source Breakdown Voltage vs. Junction Temperature

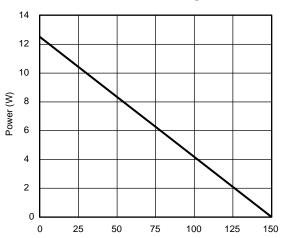


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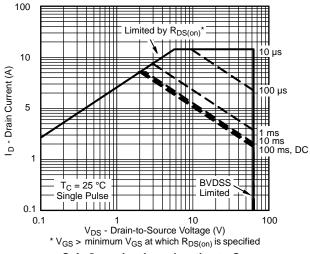




Threshold Voltage

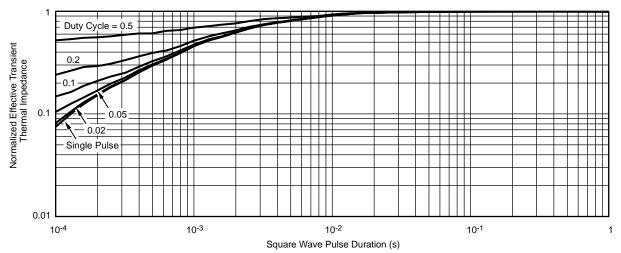


Max. Drain Current vs. Case Temperature



$\label{eq:TJ-Temperature (°C)}$ Power Derating, Junction-to-Case

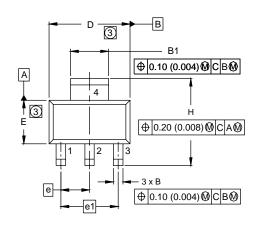


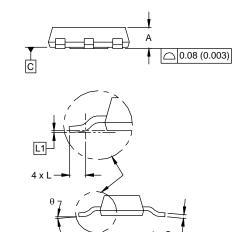


Normalized Thermal Transient Impedance, Junction-to-Case



SOT-223 (HIGH VOLTAGE)





DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
Α	1.55	1.80	0.061	0.071
В	0.65	0.85	0.026	0.033
B1	2.95	3.15	0.116	0.124
С	0.25	0.35	0.010	0.014
D	6.30	6.70	0.248	0.264
Е	3.30	3.70	0.130	0.146
е	2.30	2.30 BSC		5 BSC
e1	4.60	4.60 BSC		BSC
Н	6.71	7.29	0.264	0.287
L	0.91	-	0.036	-
L1	0.061 BSC		0.0024	4 BSC
θ	-	10'	-	10'

ECN: S-82109-Rev. A, 15-Sep-08

DWG: 5969

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Dimensions are shown in millimeters (inches).
- 3. Dimension do not include mold flash.
- 4. Outline conforms to JEDEC outline TO-261AA.

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